



K900G4 - 2U 4-node HPC Server

In the past, the amount of data a datacenter could handle was determined by physical space. However, with the rapid growth in data usage demand from cloud, as well as emerging data/computing-intensive workloads, with limitations in power, cooling and spaces, high density rack configuration is how you can best utilize the resources and maximize the compute and data capacity.

Supporting dual processors of latest Intel® Xeon® Scalable Family per node, K900G4 multi-node server solution offers relevant advantages for datacenter rack deployments from lower purchasing cost, smaller footprint, unleashed computing power, energy saving, easy serviceability and management, as well as elastic expandability in its 2U four-node high density enclosure. K900G4 could be easily scaled out to be High Performance Computing (HPC) clusters and fulfill mission critical workloads with optimized TCO. The series presents,

Unleashing Computing Power for HPC Applications

K900G4 is comprised of four high performance nodes, each with dual Intel® Xeon® Scalable Processors, TDP up to 105W, providing high density computing power up to 160 cores and 64 DDR4 DIMM slots, equal to 4TB memory capacity in a single system! Supported by latest Intel® technologies, and boosted performance, including 1.5x memory bandwidth and 2x FLOPs capability compared with previous platform, as well as faster socket interconnection through two Intel® UPI channels, K900G4 series is more than capable

Highlights -

- High memory capacity and CPU density, up to 4TB and 8 CPU counts - ideal for HPC, Datacenters and Enterprise
- Shared Infrastructure for Space, Power and Cost Efficiency
- Easy Service and Maintenance

for HPC and applicable for mission critical workloads.

Sufficient Expandability and Flexible Storage Options

Furthermore, each of K900G4 nodes is equipped with efficient scale-out capacity, providing one standard PCIe x16 slot, offering expandability from a variety of OCP 2.0 NIC card choices.

Regarding to storage configuration, K900G4 onboard supports three drive types, SAS, SATA and NVMe, up to six hot-pluggable drives per node, or 24 drives per system, plus two SATADOM modules per node. Storage RAID is available from a variety of Inventec storage card options.

Optimized TCO with Enhanced Serviceability and Reliability

The 2U4N K900G4 system delivers 4x computing power or 1/4 datacenter footprint compared with traditional 2U1N deployments, lowering the CAPEx by high density configurations. To further reduce OPex, with increased reliability and availability, K900G4 supports three dual rotor fans per node, made serviceable on the hot-swappable MLB tray. Together with the hot-pluggable 1+1 power supplies at the rear, the K900G4 system is easily maintainable.

With optimized TCO, K900G4 multi-node high density server system provides the highest efficiency of massive parallel computing for your HPC applications.



Model Name	K900G4
Positioning	High Performance Computing (HPC)
Form Factor	2U4N rack mount
Processor	Dual Socket per node; Intel® Xeon® Processor Scalable Family
Memory Slot	16x DDR4 DIMM slot per node; Up to 64x DDR4 DIMM slot per system
Chipset	Intel® C620 series
Disk Drive Bay	Primary bays: 24x 2.5" SAS/SATA/NVMe hot-plug drive
Expansion Slot	Rear per node: 1x PCIe Gen3 OCP 2.0 A+B NIC mezz 1x PCIe Gen3 x16 (Low Profile)
Network Controller	Supporting 10GbE/25GbE mezz card Inventec network OCP mezz card options: Option1: NIC-I540-10GDC (Dual port 10Gb RJ-45) Option2: NIC-I599-10GD (Dual port 10Gb SFP+)
Storage Controller	Onboard per node: 8x SATA3 6Gb/s port 2x SATADOM Inventec storage mezz card options: Option1: SAS3-3008-8i (12Gb/s)
System Management	IPMI 2.0 compliant+ KVM with Dedicated LAN
TPM	Option: 2.0
Power Supply	2200W Platinum 1+1 redundancy
Fan	Per node: 3x 4056 dual rotor fan; Six rotors with N+1 redundancy



ABOUT INVENTEC

Inventec Enterprise Business Group (EBG) was established in 1998 and has been focusing on the design and manufacturing of server systems. Inventec EBG is the key server system supplier of the global branding clients.

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